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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M7
Core Size	32-Bit Single-Core
Speed	216MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, SAI, SD, SPDIF-Rx, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	140
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	320K x 8
Voltage - Supply (Vcc/Vdd)	1.7V ~ 3.6V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f746igt6g

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**Table 2. STM32F745xx and STM32F746xx features and peripheral counts (continued)**

Peripherals		STM32F745Vx	STM32F746Vx	STM32F745Zx	STM32F746Zx	STM32F745Ix	STM32F746Ix	STM32F745Bx	STM32F746Bx	STM32F745Nx	STM32F746Nx
Communication interfaces	SPI / I ² S	4/3 (simplex) ⁽²⁾		6/3 (simplex) ⁽²⁾							
	I ² C	4									
	USART/ UART	4/4									
	USB OTG FS	Yes									
	USB OTG HS	Yes									
	CAN	2									
	SAI	2									
	SPDIFRX	4 inputs									
	SDMMC	Yes									
Camera interface		Yes									
LCD-TFT		No	Yes	No	Yes	No	Yes	No	Yes	No	Yes
Chrom-ART Accelerator™ (DMA2D)		Yes									
GPIOs		82		114		140		168			
12-bit ADC		3									
Number of channels		16		24							
12-bit DAC		Yes									
Number of channels		2									
Maximum CPU frequency		216 MHz ⁽³⁾									
Operating voltage		1.7 to 3.6 V ⁽⁴⁾									
Operating temperatures		Ambient temperatures: –40 to +85 °C /–40 to +105 °C									
		Junction temperature: –40 to + 125 °C									
Package		LQFP100 TFBGA100		WLCSP143 LQFP144		UFBGA176 LQFP176		LQFP208		TFBGA216	

- For the LQFP100 package, only FMC Bank1 is available. Bank1 can only support a multiplexed NOR/PSRAM memory using the NE1 Chip Select.
- The SPI1, SPI2 and SPI3 interfaces give the flexibility to work in an exclusive way in either the SPI mode or the I2S audio mode.
- 216 MHz maximum frequency for –40°C to + 85°C ambient temperature range (200 MHz maximum frequency for –40°C to + 105°C ambient temperature range).
- VDD/VDDA minimum value of 1.7 V is obtained when the internal reset is OFF (refer to [Section 2.17.2: Internal reset OFF](#)).

2.3 Embedded Flash memory

The STM32F745xx and STM32F746xx devices embed a Flash memory of up to 1 Mbyte available for storing programs and data.

2.4 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code using a configurable generator polynomial value and size.

Among other applications, CRC-based techniques are used to verify the data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a mean of verifying the Flash memory integrity. The CRC calculation unit helps to compute a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

2.5 Embedded SRAM

All the devices features:

- System SRAM up to 320 Kbytes:
 - SRAM1 on AHB bus Matrix: 240 Kbytes
 - SRAM2 on AHB bus Matrix: 16 Kbytes
 - DTCM-RAM on TCM interface (Tightly Coupled Memory interface): 64 Kbytes for critical real-time data.
- Instruction RAM (ITCM-RAM) 16 Kbytes:
 - It is mapped on TCM interface and reserved only for CPU Execution/Instruction useful for critical real-time routines.

The Data TCM RAM is accessible by the GP-DMA's and peripherals DMA's through specific AHB slave of the CPU. The TCM RAM instruction is reserved only for CPU. It is accessed at CPU clock speed with 0-wait states.

- 4 Kbytes of backup SRAM
 - This area is accessible only from the CPU. Its content is protected against possible unwanted write accesses, and is retained in Standby or VBAT mode.

2.6 AXI-AHB bus matrix

The STM32F745xx and STM32F746xx system architecture is based on 2 sub-systems:

- An AXI to multi AHB bridge converting AXI4 protocol to AHB-Lite protocol:
 - 3x AXI to 32-bit AHB bridges connected to AHB bus matrix
 - 1x AXI to 64-bit AHB bridge connected to the embedded flash
- A multi-AHB Bus-Matrix:
 - The 32-bit multi-AHB bus matrix interconnects all the masters (CPU, DMA's, Ethernet, USB HS, LCD-TFT, and DMA2D) and the slaves (Flash memory, RAM, FMC, Quad-SPI, AHB and APB peripherals) and ensures a seamless and an efficient operation even when several high-speed peripherals work simultaneously.

2.22.3 Basic timers TIM6 and TIM7

These timers are mainly used for DAC trigger and waveform generation. They can also be used as a generic 16-bit time base.

TIM6 and TIM7 support independent DMA request generation.

2.22.4 Low-power timer (LPTIM1)

The low-power timer has an independent clock and is running also in Stop mode if it is clocked by LSE, LSI or an external clock. It is able to wakeup the devices from Stop mode.

This low-power timer supports the following features:

- 16-bit up counter with 16-bit autoreload register
- 16-bit compare register
- Configurable output: pulse, PWM
- Continuous / one-shot mode
- Selectable software / hardware input trigger
- Selectable clock source:
 - Internal clock source: LSE, LSI, HSI or APB clock
 - External clock source over LPTIM input (working even with no internal clock source running, used by the Pulse Counter Application)
- Programmable digital glitch filter
- Encoder mode

2.22.5 Independent watchdog

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 32 kHz internal RC and as it operates independently from the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes.

2.22.6 Window watchdog

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

2.22.7 SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard downcounter. It features:

- A 24-bit downcounter
- Autoreload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source.

Table 8. USART implementation (continued)

features ⁽¹⁾	USART1/2/3/6	UART4/5/7/8
Smartcard mode	X	-
Single-wire half-duplex communication	X	X
IrDA SIR ENDEC block	X	X
LIN mode	X	X
Dual clock domain	X	X
Receiver timeout interrupt	X	X
Modbus communication	X	X
Auto baud rate detection	X	X
Driver Enable	X	X

1. X: supported.

2.25 Serial peripheral interface (SPI)/inter- integrated sound interfaces (I2S)

The devices feature up to six SPIs in slave and master modes in full-duplex and simplex communication modes. SPI1, SPI4, SPI5, and SPI6 can communicate at up to 50 Mbits/s, SPI2 and SPI3 can communicate at up to 25 Mbit/s. The 3-bit prescaler gives 8 master mode frequencies and the frame is configurable from 4 to 16 bits. The SPI interfaces support NSS pulse mode, TI mode and Hardware CRC calculation. All SPIs can be served by the DMA controller.

Three standard I²S interfaces (multiplexed with SPI1, SPI2 and SPI3) are available. They can be operated in master or slave mode, in simplex communication modes, and can be configured to operate with a 16-/32-bit resolution as an input or output channel. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When either or both of the I²S interfaces is/are configured in master mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling frequency.

All I2Sx can be served by the DMA controller.

2.26 Serial audio interface (SAI)

The devices embed two serial audio interfaces.

The serial audio interface is based on two independent audio subblocks which can operate as transmitter or receiver with their FIFO. Many audio protocols are supported by each block: I2S standards, LSB or MSB-justified, PCM/DSP, TDM, AC'97 and SPDIF output, supporting audio sampling frequencies from 8 kHz up to 192 kHz. Both subblocks can be configured in master or in slave mode.

In master mode, the master clock can be output to the external DAC/CODEC at 256 times of the sampling frequency.

The two sub-blocks can be configured in synchronous mode when full-duplex mode is required.

The major features are:

- Combined Rx and Tx FIFO size of 4 Kbytes with dynamic FIFO sizing
- Support of the session request protocol (SRP) and host negotiation protocol (HNP)
- 8 bidirectional endpoints
- 16 host channels with periodic OUT support
- Software configurable to OTG1.3 and OTG2.0 modes of operation
- USB 2.0 LPM (Link Power Management) support
- Internal FS OTG PHY support
- External HS or HS OTG operation supporting ULPI in SDR mode. The OTG PHY is connected to the microcontroller ULPI port through 12 signals. It can be clocked using the 60 MHz output.
- Internal USB DMA
- HNP/SNP/IP inside (no need for any external resistor)
- for OTG/Host modes, a power switch is needed in case bus-powered devices are connected

2.35 High-definition multimedia interface (HDMI) - consumer electronics control (CEC)

The device embeds a HDMI-CEC controller that provides hardware support for the Consumer Electronics Control (CEC) protocol (Supplement 1 to the HDMI standard).

This protocol provides high-level control functions between all audiovisual products in an environment. It is specified to operate at low speeds with minimum processing and memory overhead. It has a clock domain independent from the CPU clock, allowing the HDMI-CEC controller to wakeup the MCU from Stop mode on data reception.

2.36 Digital camera interface (DCMI)

The devices embed a camera interface that can connect with camera modules and CMOS sensors through an 8-bit to 14-bit parallel interface, to receive video data. The camera interface can sustain a data transfer rate up to 54 Mbyte/s at 54 MHz. It features:

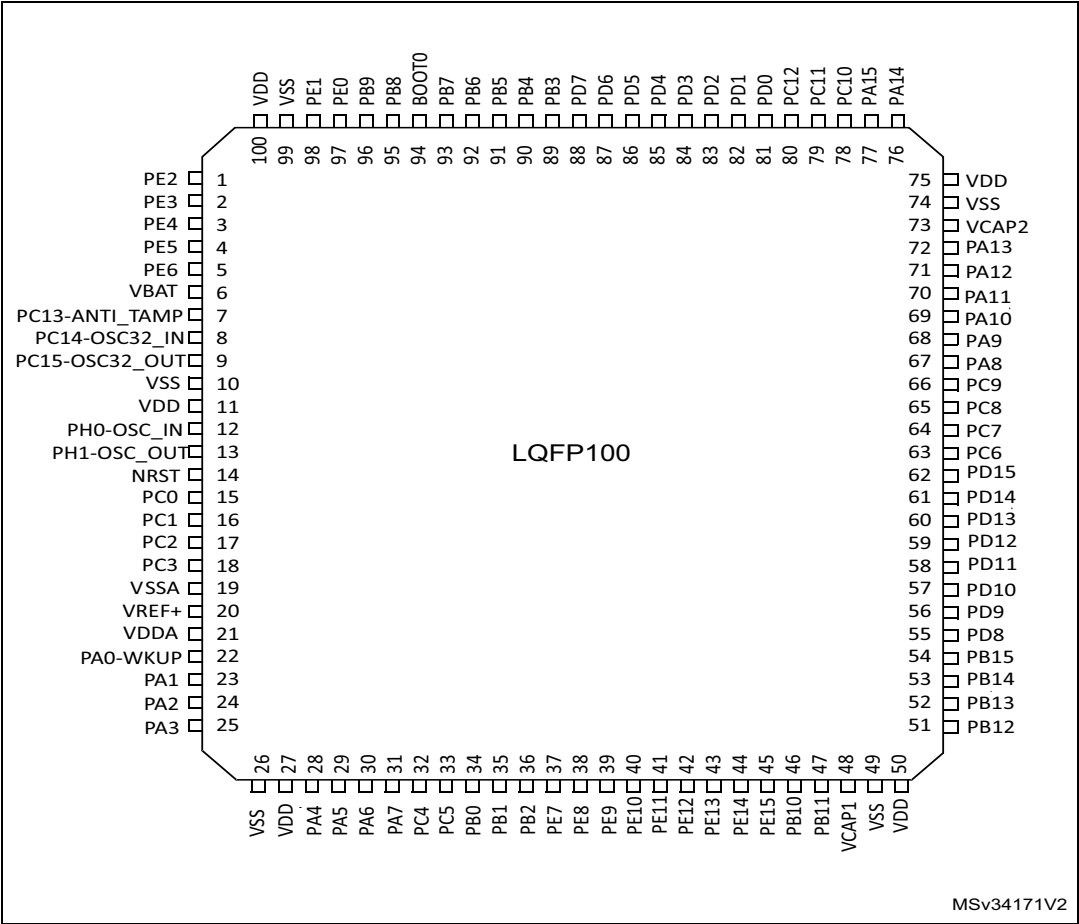
- Programmable polarity for the input pixel clock and synchronization signals
- Parallel data communication can be 8-, 10-, 12- or 14-bit
- Supports 8-bit progressive video monochrome or raw bayer format, YCbCr 4:2:2 progressive video, RGB 565 progressive video or compressed data (like JPEG)
- Supports continuous mode or snapshot (a single frame) mode
- Capability to automatically crop the image

2.37 Random number generator (RNG)

All devices embed an RNG that delivers 32-bit random numbers generated by an integrated analog circuit.

3 Pinouts and pin description

Figure 11. STM32F74xVx LQFP100 pinout



2. The above figure shows the package top view.

Table 10. STM32F745xx and STM32F746xx pin and ball definition (continued)

Pin Number								Pin name (function after reset) ⁽¹⁾	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	TFBGA100	WLCSP143	LQFP144	UFBGA176	LQFP176	LQFP208	TFBGA216						
4	D3	D9	4	B2	4	4	B1	PE5	I/O	FT	-	TRACED2, TIM9_CH1, SPI4_MISO, SAI1_SCK_A, FMC_A21, DCMI_D6, LCD_G0, EVENTOUT	-
5	E3	E8	5	B3	5	5	B2	PE6	I/O	FT	-	TRACED3, TIM1_BKIN2, TIM9_CH2, SPI4_MOSI, SAI1_SD_A, SAI2_MCK_B, FMC_A22, DCMI_D7, LCD_G1, EVENTOUT	-
-	-	-	-	-	-	-	G6	VSS	S	-	-	-	-
-	-	-	-	-	-	-	F5	VDD	S	-	-	-	-
6	B2	C11	6	C1	6	6	C1	VBAT	S	-	-	-	-
-	-	-	-	D2	7	7	C2	PI8	I/O	FT	(2) (3)	EVENTOUT	RTC_TAMP2/ RTC_TS,WK UP5
7	A2	D10	7	D1	8	8	D1	PC13	I/O	FT	(2) (3)	EVENTOUT	RTC_TAMP1/ RTC_TS/RTC _OUT,WKUP 4
8	A1	D11	8	E1	9	9	E1	PC14- OSC32_I N(PC14)	I/O	FT	(2) (3)	EVENTOUT	OSC32_IN
9	B1	E11	9	F1	10	10	F1	PC15- OSC32_ OUT(PC 15)	I/O	FT	(2) (3)	EVENTOUT	OSC32_OUT
-	-	-	-	-	-	-	G5	VDD	S	-	-	-	-
-	-	-	-	D3	11	11	E4	PI9	I/O	FT	-	CAN1_RX, FMC_D30, LCD_VSYNC, EVENTOUT	-
-	-	-	-	E3	12	12	D5	PI10	I/O	FT	-	ETH_MII_RX_ER, FMC_D31, LCD_HSYNC, EVENTOUT	-

Table 10. STM32F745xx and STM32F746xx pin and ball definition (continued)

Pin Number								Pin name (function after reset) ⁽¹⁾	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	TFBGA100	WLCSP143	LQFP144	UFBGA176	LQFP176	LQFP208	TFBGA216						
18	F3	J9	29	M5	35	38	L4	PC3	I/O	FT	(4)	SPI2_MOSI/I2S2_SD, OTG_HS_ULPI_NXT, ETH_MII_TX_CLK, FMC_SDCKE0, EVENTOUT	ADC123_IN1 3
-	-	G7	30	G3	36	39	J5	VDD	S	-	-	-	-
-	-	-	-	-	-	-	J6	VSS	S	-	-	-	-
19	G1	K10	31	M1	37	40	M1	VSSA	S	-	-	-	-
-	-	-	-	N1	-	-	N1	VREF-	S	-	-	-	-
20	-	L11	32	P1	38	41	P1	VREF+	S	-	-	-	-
21	H1	L10	33	R1	39	42	R1	VDDA	S	-	-	-	-
22	G2	K9	34	N3	40	43	N3	PA0- WKUP(P A0)	I/O	FT	(5)	TIM2_CH1/TIM2_ETR, TIM5_CH1, TIM8_ETR, USART2_CTS, UART4_TX, SAI2_SD_B, ETH_MII_CRS, EVENTOUT	ADC123_IN0, WKUP1 ⁽⁴⁾
23	H2	K8	35	N2	41	44	N2	PA1	I/O	FT	(4)	TIM2_CH2, TIM5_CH2, USART2 RTS, UART4_RX, QUADSPI_BK1_IO3, SAI2_MCK_B, ETH_MII_RX_CLK/ETH_ RMII_REF_CLK, LCD_R2, EVENTOUT	ADC123_IN1
24	J2	L9	36	P2	42	45	P2	PA2	I/O	FT	(4)	TIM2_CH3, TIM5_CH3, TIM9_CH1, USART2_TX, SAI2_SCK_B, ETH_MDIO, LCD_R1, EVENTOUT	ADC123_IN2, WKUP2
-	-	-	-	F4	43	46	K4	PH2	I/O	FT		LPTIM1_IN2, QUADSPI_BK2_IO0, SAI2_SCK_B, ETH_MII_CRS, FMC_SDCKE0, LCD_R0, EVENTOUT	-

Table 10. STM32F745xx and STM32F746xx pin and ball definition (continued)

Pin Number								Pin name (function after reset) ⁽¹⁾	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	TFBGA100	WLCSP143	LQFP144	UFBGA176	LQFP176	LQFP208	TFBGA216						
41	H6	K4	64	P10	74	85	P10	PE11	I/O	FT	-	TIM1_CH2, SPI4_NSS, SAI2_SD_B, FMC_D8, LCD_G3, EVENTOUT	-
42	J6	L4	65	R10	75	86	R10	PE12	I/O	FT	-	TIM1_CH3N, SPI4_SCK, SAI2_SCK_B, FMC_D9, LCD_B4, EVENTOUT	-
43	K6	N4	66	N11	76	87	R12	PE13	I/O	FT	-	TIM1_CH3, SPI4_MISO, SAI2_FS_B, FMC_D10, LCD_DE, EVENTOUT	-
44	G7	M4	67	P11	77	88	P11	PE14	I/O	FT	-	TIM1_CH4, SPI4_MOSI, SAI2_MCK_B, FMC_D11, LCD_CLK, EVENTOUT	-
45	H7	L3	68	R11	78	89	R11	PE15	I/O	FT	-	TIM1_BKIN, FMC_D12, LCD_R7, EVENTOUT	-
46	J7	M3	69	R12	79	90	P12	PB10	I/O	FT	-	TIM2_CH3, I2C2_SCL, SPI2_SCK/I2S2_CK, USART3_TX, OTG_HS_ULPI_D3, ETH_MII_RX_ER, LCD_G4, EVENTOUT	-
47	K7	N3	70	R13	80	91	R13	PB11	I/O	FT	-	TIM2_CH4, I2C2_SDA, USART3_RX, OTG_HS_ULPI_D4, ETH_MII_TX_EN/ETH_R MII_TX_EN, LCD_G5, EVENTOUT	-
48	F8	N2	71	M10	81	92	L11	VCAP_1	S	-	-	-	-
49	-	H2	-	-	-	93	K9	VSS	S	-	-	-	-
50	-	J6	72	N10	82	94	L10	VDD	S	-	-	-	-
-	-	-	-	-	-	95	M14	PJ5	I/O	FT	-	LCD_R6, EVENTOUT	-
-	-	-	-	M11	83	96	P13	PH6	I/O	FT	-	I2C2_SMBA, SPI5_SCK, TIM12_CH1, ETH_MII_RXD2, FMC_SDNE1, DCMI_D8, EVENTOUT	-

Table 12. STM32F745xx and STM32F746xx alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS	TIM1/2	TIM3/4/5	TIM8/9/10/ 11/LPTIM 1/CEC	I2C1/2/3/ 4/CEC	SPI1/2/3/ 4/5/6	SPI3/ SAI1	SPI2/3/U SART1/2/ 3/UART5/ SPDIFRX	SAI2/US ART6/UA RT4/5/7/8 /SPDIFR X	CAN1/2/T IM12/13/ 14/QUAD SPI/LCD	SAI2/QU ADSPI/O TG2_HS/ OTG1_FS	ETH/ OTG1_FS	FMC/SD MMC1/O TG2_FS	DCMI	LCD	SYS
Port J	PJ7	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G0	EVEN TOUT
	PJ8	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G1	EVEN TOUT
	PJ9	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G2	EVEN TOUT
	PJ10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G3	EVEN TOUT
	PJ11	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G4	EVEN TOUT
	PJ12	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B0	EVEN TOUT
	PJ13	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B1	EVEN TOUT
	PJ14	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B2	EVEN TOUT
	PJ15	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B3	EVEN TOUT

Table 13. STM32F745xx and STM32F746xx register boundary addresses (continued)

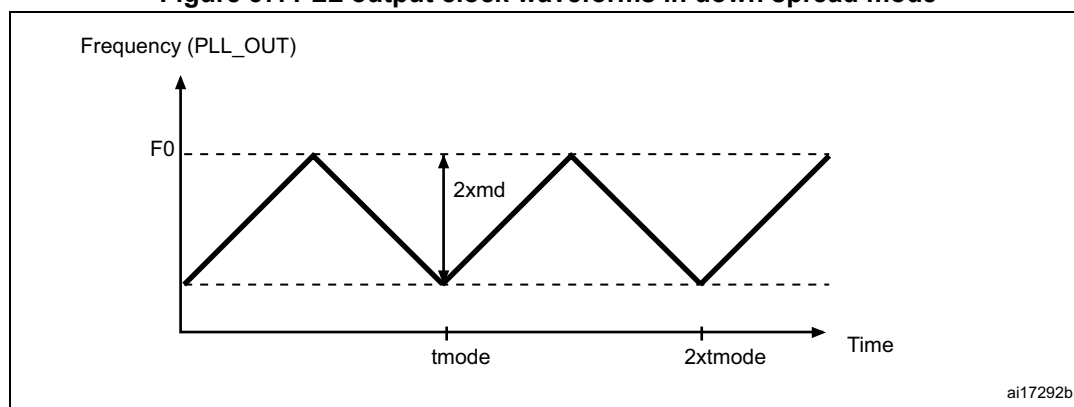
Bus	Boundary address	Peripheral
	0x4000 8000 - 0x4000 FFFF	Reserved
APB1	0x4000 7C00 - 0x4000 7FFF	UART8
	0x4000 7800 - 0x4000 7BFF	UART7
	0x4000 7400 - 0x4000 77FF	DAC
	0x4000 7000 - 0x4000 73FF	PWR
	0x4000 6C00 - 0x4000 6FFF	HDMI-CEC
	0x4000 6800 - 0x4000 6BFF	CAN2
	0x4000 6400 - 0x4000 67FF	CAN1
	0x4000 6000 - 0x4000 63FF	I2C4
	0x4000 5C00 - 0x4000 5FFF	I2C3
	0x4000 5800 - 0x4000 5BFF	I2C2
	0x4000 5400 - 0x4000 57FF	I2C1
	0x4000 5000 - 0x4000 53FF	UART5
	0x4000 4C00 - 0x4000 4FFF	UART4
	0x4000 4800 - 0x4000 4BFF	USART3
	0x4000 4400 - 0x4000 47FF	USART2
	0x4000 4000 - 0x4000 43FF	SPDIFRX
	0x4000 3C00 - 0x4000 3FFF	SPI3 / I2S3
	0x4000 3800 - 0x4000 3BFF	SPI2 / I2S2
	0x4000 3400 - 0x4000 37FF	Reserved
	0x4000 3000 - 0x4000 33FF	IWDG
	0x4000 2C00 - 0x4000 2FFF	WWDG
	0x4000 2800 - 0x4000 2BFF	RTC & BKP Registers
	0x4000 2400 - 0x4000 27FF	LPTIM1
	0x4000 2000 - 0x4000 23FF	TIM14
	0x4000 1C00 - 0x4000 1FFF	TIM13
	0x4000 1800 - 0x4000 1BFF	TIM12
	0x4000 1400 - 0x4000 17FF	TIM7
	0x4000 1000 - 0x4000 13FF	TIM6
	0x4000 0C00 - 0x4000 0FFF	TIM5
	0x4000 0800 - 0x4000 0BFF	TIM4
	0x4000 0400 - 0x4000 07FF	TIM3
	0x4000 0000 - 0x4000 03FF	TIM2

Table 26. Typical and maximum current consumption in Run mode, code with data processing running from Flash memory or SRAM on AXI (L1-cache disabled), regulator ON

Symbol	Parameter	Conditions	f _{HCLK} (MHz)	Typ	Max ⁽¹⁾			Unit
					TA= 25 °C	TA=85 °C	TA=105 °C	
I _{DD}	Supply current in RUN mode	All peripherals enabled ⁽²⁾⁽³⁾	216	181	210	233	-	mA
			200	168	194	216	234	
			180	153	176	192	206	
			168	136	157	172	184	
			144	109	125	137	148	
			60	53	61	73	84	
			25	26	30	41	52	
		All peripherals disabled ⁽³⁾	216	105	121	145	-	
			200	98	112	134	153	
			180	90	103	119	132	
			168	81	93	107	120	
			144	67	76	88	89	
			60	34	40	51	62	
			25	17	20	31	42	

1. Guaranteed by characterization results.
2. When analog peripheral blocks such as ADCs, DACs, HSE, LSE, HSI, or LSI are ON, an additional power consumption should be considered.
3. When the ADC is ON (ADON bit set in the ADC_CR2 register), add an additional power consumption of 1.73 mA per ADC for the analog part.

Figure 37. PLL output clock waveforms in down spread mode



5.3.13 Memory characteristics

Flash memory

The characteristics are given at $T_A = -40$ to $105\text{ }^{\circ}\text{C}$ unless otherwise specified.

The devices are shipped to customers with the Flash memory erased.

Table 47. Flash memory characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{DD}	Supply current	Write / Erase 8-bit mode, $V_{DD} = 1.7\text{ V}$	-	14	-	mA
		Write / Erase 16-bit mode, $V_{DD} = 2.1\text{ V}$	-	17	-	
		Write / Erase 32-bit mode, $V_{DD} = 3.3\text{ V}$	-	24	-	

Table 48. Flash memory programming

Symbol	Parameter	Conditions	Min ⁽¹⁾	Typ	Max ⁽¹⁾	Unit
t_{prog}	Word programming time	Program/erase parallelism (PSIZE) = x 8/16/32	-	16	100 ⁽²⁾	μs
$t_{ERASE32KB}$	Sector (32 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	400	800	ms
		Program/erase parallelism (PSIZE) = x 16	-	250	600	
		Program/erase parallelism (PSIZE) = x 32	-	200	500	
$t_{ERASE128KB}$	Sector (128 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	1100	2400	ms
		Program/erase parallelism (PSIZE) = x 16	-	800	1400	
		Program/erase parallelism (PSIZE) = x 32	-	500	1100	

5.3.15 Absolute maximum ratings (electrical sensitivity)

Based on three different tests (ESD, LU) using specific measurement methods, the device is stressed in order to determine its performance in terms of electrical sensitivity.

Electrostatic discharge (ESD)

Electrostatic discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts × (n+1) supply pins). This test conforms to the ANSI/ESDA/JEDEC JS-001-2012 and ANSI/ESD S5.3.1-2009 standards.

Table 53. ESD absolute maximum ratings

Symbol	Ratings	Conditions	Class	Maximum value ⁽¹⁾	Unit
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	$T_A = +25\text{ °C}$ conforming to ANSI/ESDA/JEDEC JS-001-2012	2	2000	V
$V_{ESD(CDM)}$	Electrostatic discharge voltage (charge device model)	$T_A = +25\text{ °C}$ conforming to ANSI/ESD S5.3.1-2009, LQFP100, LQFP144, LQFP176, LQFP208, WLCSP143, UFBGA176, TFBGA100 and TFBGA216 packages	C3	250	

1. Guaranteed by characterization results.

Static latchup

Two complementary static tests are required on six parts to assess the latchup performance:

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin

These tests are compliant with EIA/JESD 78A IC latchup standard.

Table 54. Electrical sensitivities

Symbol	Parameter	Conditions	Class
LU	Static latch-up class	$T_A = +105\text{ °C}$ conforming to JESD78A	II level A

5.3.16 I/O current injection characteristics

As a general rule, current injection to the I/O pins, due to external voltage below V_{SS} or above V_{DD} (for standard, 3 V-capable I/O pins) should be avoided during normal product operation. However, in order to give an indication of the robustness of the microcontroller in cases when abnormal injection accidentally happens, susceptibility tests are performed on a sample basis during device characterization.

Functional susceptibility to I/O current injection

While a simple application is executed on the device, the device is stressed by injecting current into the I/O pins programmed in floating input mode. While current is injected into the I/O pin, one at a time, the device is checked for functional failures.

Table 58. I/O AC characteristics⁽¹⁾⁽²⁾ (continued)

OSPEEDRy [1:0] bit value ⁽¹⁾	Symbol	Parameter	Conditions	Min	Typ	Max	Unit
11	$f_{\max(\text{IO})\text{out}}$	Maximum frequency ⁽³⁾	$C_L = 30 \text{ pF}, V_{DD} \geq 2.7 \text{ V}$	-	-	100 ⁽⁴⁾	MHz
			$C_L = 30 \text{ pF}, V_{DD} \geq 1.8 \text{ V}$	-	-	50	
			$C_L = 30 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	42.5	
			$C_L = 10 \text{ pF}, V_{DD} \geq 2.7 \text{ V}$	-	-	180 ⁽⁴⁾	
			$C_L = 10 \text{ pF}, V_{DD} \geq 1.8 \text{ V}$	-	-	100	
			$C_L = 10 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	72.5	
	$t_{f(\text{IO})\text{out}}/$ $t_{r(\text{IO})\text{out}}$	Output high to low level fall time and output low to high level rise time	$C_L = 30 \text{ pF}, V_{DD} \geq 2.7 \text{ V}$	-	-	4	ns
			$C_L = 30 \text{ pF}, V_{DD} \geq 1.8 \text{ V}$	-	-	6	
			$C_L = 30 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	7	
			$C_L = 10 \text{ pF}, V_{DD} \geq 2.7 \text{ V}$	-	-	2.5	
			$C_L = 10 \text{ pF}, V_{DD} \geq 1.8 \text{ V}$	-	-	3.5	
			$C_L = 10 \text{ pF}, V_{DD} \geq 1.7 \text{ V}$	-	-	4	
-	$t_{\text{EXTI}pw}$	Pulse width of external signals detected by the EXTI controller	-	10	-	-	ns

1. Guaranteed by design.
2. The I/O speed is configured using the OSPEEDRy[1:0] bits. Refer to the STM32F75xxx and STM32F74xxx reference manual for a description of the GPIOx_SPEEDR GPIO port output speed register.
3. The maximum frequency is defined in [Figure 39](#).
4. For maximum frequencies above 50 MHz and $V_{DD} > 2.4 \text{ V}$, the compensation cell should be used.

Figure 39. I/O AC characteristics definition

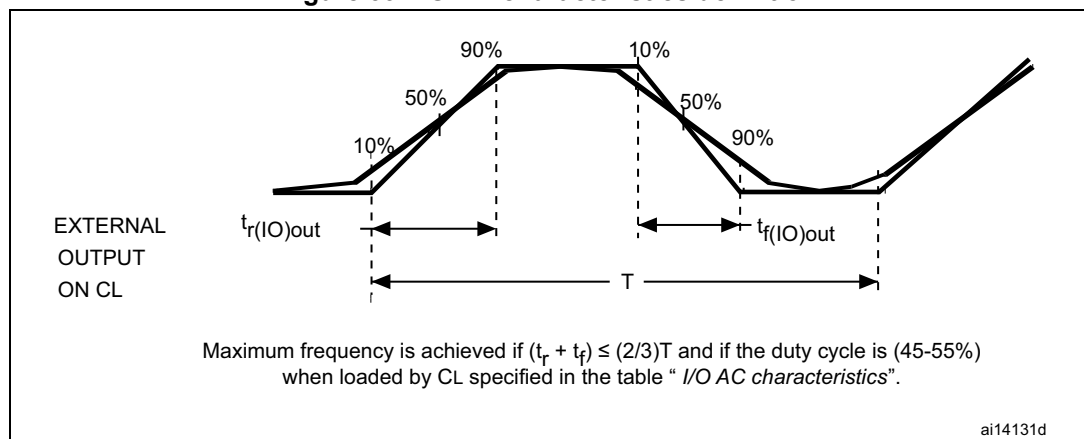


Table 62. ADC characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{VREF+}^{(2)}$	ADC V_{REF} DC current consumption in conversion mode	-	-	300	500	μA
$I_{VDDA}^{(2)}$	ADC V_{DDA} DC current consumption in conversion mode	-	-	1.6	1.8	mA

- V_{DDA} minimum value of 1.7 V is obtained with the use of an external power supply supervisor (refer to [Section 2.17.2: Internal reset OFF](#)).
- Guaranteed by characterization results.
- V_{REF+} is internally connected to V_{DDA} and V_{REF-} is internally connected to V_{SSA} .
- R_{ADC} maximum value is given for $V_{DD}=1.7$ V, and minimum value for $V_{DD}=3.3$ V.
- For external triggers, a delay of $1/f_{PCLK2}$ must be added to the latency specified in [Table 62](#).

Equation 1: R_{AIN} max formula

$$R_{AIN} = \frac{(k - 0.5)}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$$

The formula above ([Equation 1](#)) is used to determine the maximum external impedance allowed for an error below 1/4 of LSB. $N = 12$ (from 12-bit resolution) and k is the number of sampling periods defined in the ADC_SMPR1 register.

Table 63. ADC static accuracy at $f_{ADC} = 18$ MHz

Symbol	Parameter	Test conditions	Typ	Max ⁽¹⁾	Unit
ET	Total unadjusted error	$f_{ADC} = 18$ MHz $V_{DDA} = 1.7$ to 3.6 V $V_{REF} = 1.7$ to 3.6 V $V_{DDA} - V_{REF} < 1.2$ V	± 3	± 4	LSB
EO	Offset error		± 2	± 3	
EG	Gain error		± 1	± 3	
ED	Differential linearity error		± 1	± 2	
EL	Integral linearity error		± 2	± 3	

- Guaranteed by characterization results.

Table 64. ADC static accuracy at $f_{ADC} = 30$ MHz

Symbol	Parameter	Test conditions	Typ	Max ⁽¹⁾	Unit
ET	Total unadjusted error	$f_{ADC} = 30$ MHz, $R_{AIN} < 10$ k Ω , $V_{DDA} = 2.4$ to 3.6 V, $V_{REF} = 1.7$ to 3.6 V, $V_{DDA} - V_{REF} < 1.2$ V	± 2	± 5	LSB
EO	Offset error		± 1.5	± 2.5	
EG	Gain error		± 1.5	± 4	
ED	Differential linearity error		± 1	± 2	
EL	Integral linearity error		± 1.5	± 3	

- Guaranteed by characterization results.

1. Guaranteed by characterization results.

Table 95. Asynchronous multiplexed PSRAM/NOR write-NWAIT timings⁽¹⁾

Symbol	Parameter	Min	Max	Unit
$t_{w(NE)}$	FMC_NE low time	$9T_{HCLK}$	$9T_{HCLK}+1.5$	ns
$t_{w(NWE)}$	FMC_NWE low time	$7T_{HCLK}-0.5$	$7T_{HCLK}+0.5$	
$t_{su(NWAIT_NE)}$	FMC_NWAIT valid before FMC_NEx high	$6T_{HCLK}+2$	-	
$t_{h(NE_NWAIT)}$	FMC_NEx hold time after FMC_NWAIT invalid	$4T_{HCLK}-1$	-	

1. Guaranteed by characterization results.

Synchronous waveforms and timings

[Figure 62](#) through [Figure 65](#) represent synchronous waveforms and [Table 96](#) through [Table 99](#) provide the corresponding timings. The results shown in these tables are obtained with the following FMC configuration:

- BurstAccessMode = FMC_BurstAccessMode_Enable;
- MemoryType = FMC_MemoryType_CRAM;
- WriteBurst = FMC_WriteBurst_Enable;
- CLKDivision = 1;
- DataLatency = 1 for NOR Flash; DataLatency = 0 for PSRAM
- CL = 30 pF on data and address lines. CL = 10 pF on FMC_CLK unless otherwise specified.

In all timing tables, the T_{HCLK} is the HCLK clock period.

- For $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, maximum FMC_CLK = 108 MHz at CL=20 pF or 90 MHz at CL=30 pF (on FMC_CLK).
- For $1.71\text{ V} \leq V_{DD} < 2.7\text{ V}$, maximum FMC_CLK = 70 MHz at CL=10 pF (on FMC_CLK).

7 Part numbering

Table 125. Ordering information scheme

Example:	STM32	F	746	V	G	T	6	xxx
Device family								
STM32 = ARM-based 32-bit microcontroller								
Product type								
F = general-purpose								
Device subfamily								
745= STM32F745xx, USB OTG FS/HS, camera interface Ethernet 746= STM32F746xx, USB OTG FS/HS, camera interface, Ethernet, LCD-TFT								
Pin count								
V = 100 pins Z = 143 and 144 pins I = 176 pins B = 208 pins N = 216 pins								
Flash memory size								
E = 512 Kbytes of Flash memory G = 1024 Kbytes of Flash memory								
Package								
T = LQFP K = UFBGA H = TFBGA Y = WLCSP								
Temperature range								
6 = Industrial temperature range, −40 to 85 °C. 7 = Industrial temperature range, −40 to 105 °C.								
Options								
xxx = programmed parts TR = tape and reel								

For a list of available options (speed, package, etc.) or for further information on any aspect of this device, please contact your nearest ST sales office.